Epoxy resin 904AB

I. Statement of purpose

Epoxy resin 904AB is a two-group epoxy resin <u>neutral soft adhesive</u>, high arc arc surface adhesive, strong adhesion, after curing a certain degree of toughness, moderate softness, room temperature or heating curing softness is good, the surface is good, cell phone shells adhesive diamonds, crafts adhesive diamonds, jewelry inlaid with diamonds, <u>high arc product drop glue</u>, <u>hair clips</u>, <u>lamps and lanterns</u> on the surface of the encapsulation or electronic parts of the transparent perfusion.

II. Pre-sclerotic properties.

A glue 904A

Curing agent 904B

Color: colorless and transparent colorless and transparent

weight: 1.15 0.96

Viscosity 25°C: <u>2500-3500CPS</u> <u>1500MAXCPS</u>

III. Conditions of use

1) mixing ratio: A: B=100: 50 (weight ratio)

2)hardening condition: 25[°]C×24H-28H (2g)

3) usable time: $25^{\circ}\text{C} \times 50 \text{min} (100 \text{g})$

IV. Methods of use.

- 1. Working environment: keep the glue container clean, A, B components strictly according to the weight ratio, accurate weighing, clockwise along the inner wall of the container to mix well and stand for 3-5 minutes after use.
- 2. Depending on the operating time and dosage of the glue, to avoid waste. When the temperature is lower than 15 °C, please preheat the A glue to 30 °C before glue mixing, easy to operate (low temperature A glue will become thicker); after use must be sealed barrel lid, to avoid moisture absorption caused by the product scrap.
- 3. When the relative humidity is greater than 85%, the surface of the cured material is easy to absorb water in the air, forming a layer of white mist, so when the relative humidity is greater than 85%, it is not suitable for room temperature curing, it is recommended to use the heating curing.

The above performance data are typical data measured in a laboratory environment with a temperature of 25°C and a humidity of 70%, and are for customers' reference only.